

Handling Requirements

All surface mount products which do not meet Level 1 moisture sensitivity requirements are processed through dry bake and pack procedure. The necessary data is recorded on the caution label of each shipment. The following Peregrine-offered package types are moisture sensitivity Level 3:

8-lead TSSOP, 20-lead TSSOP, 24-lead TSSOP, 44-lead PLCC and 48-lead QFN packages.

Level 3 Caution Label

The caution label should contain the following information for Level 3 devices:

1. Calculated shelf life in sealed bag: 12 months at <math><40\text{ }^{\circ}\text{C}</math> and <math><90\%</math> relative humidity (RH)
2. Peak package body temperature is 225 °C.
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
 - a) Be mounted within 168 hours of factory conditions <math><30\text{ }^{\circ}\text{C}/60\%</math> RH, **or**
 - b) Be stored at <math><10\%</math> RH
4. Devices require bake, before mounting, if:
 - a) Humidity Indicator Card is > 10% when read at $23 \pm 5\text{ }^{\circ}\text{C}$
 - b) 3a or 3b are not met
5. If baking is required, devices may be baked for 48 hours at $125 +5/-0\text{ }^{\circ}\text{C}$

Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC-J-STD-033 for bake procedure.

Level and Body temperature defined by:
IPC/JEDEC-J-STD-020

For Dry Bake Procedures, see:
IPC/JEDEC-J-STD-033

Operator must observe ESD precautions per ESD Control Procedure and Parts Handling and shipping Procedure.